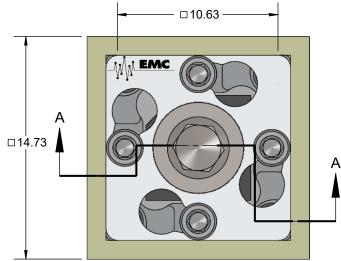
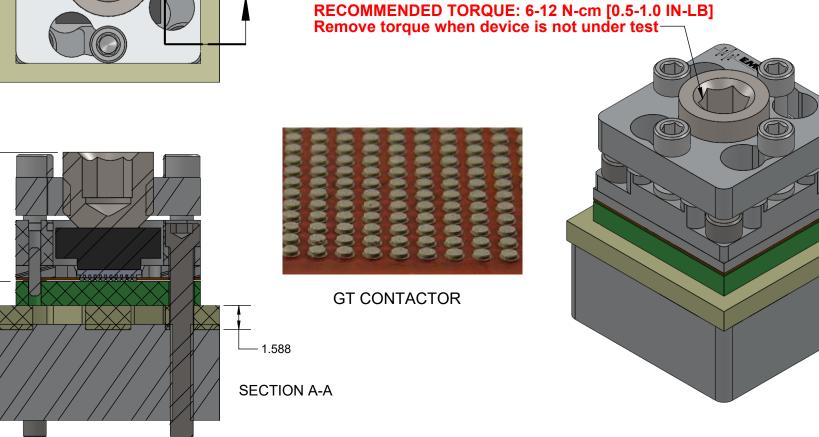
GHz BGA Socket - Direct mount, solderless



Features

- Directly mounts to target PCB (needs tooling holes) with hardware
 Minimum real estate required
 Compression plate distributes forces evenly
 Easily removable swivel socket lid



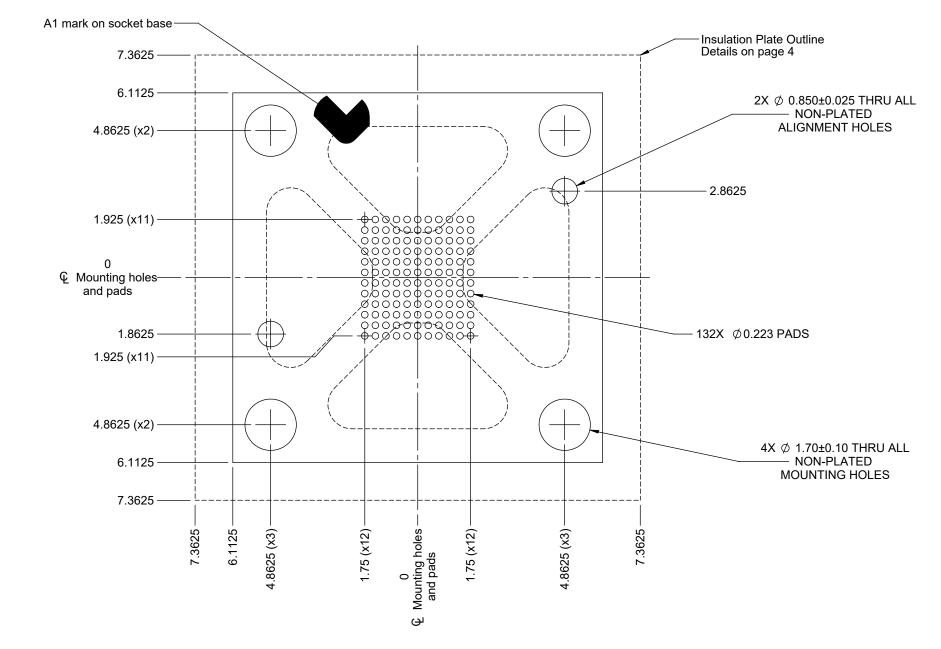
Description: GT-BGA 0.35mm pitch

8.5

8.8

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

GT-BGA-2021 Drawing	Finish: N/A	STATUS: Released	SHEET: 1 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com		ENG: B. Schatz	DRAWN BY: M. Raske	SCALE: 4:1
	Weight 0.00	FILE: GT-BGA-2021 Dwg	GT-BGA-2021 Dwg DATE: 09/18/2015	



Description: Recommended PCB Layout

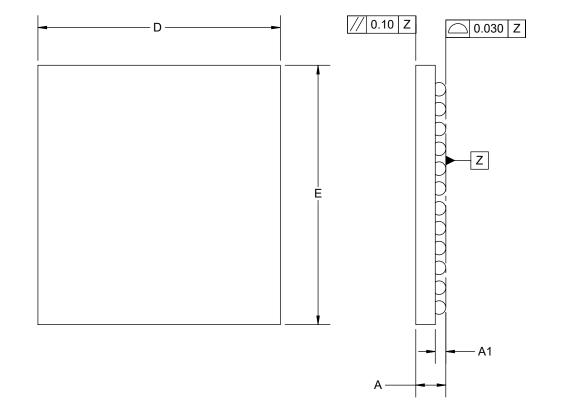
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. <u>Tolerances:</u> Hole diameters ± 0.03 mm [$\pm 0.001^{"}$], Hole and pad locations ± 0.025 mm [$\pm 0.001^{"}$], substrate thickness tolerance $\pm 10\%$, all other tolerances ± 0.13 mm [$\pm 0.005^{"}$] unless stated otherwise. Materials and specifications are subject to change without notice.

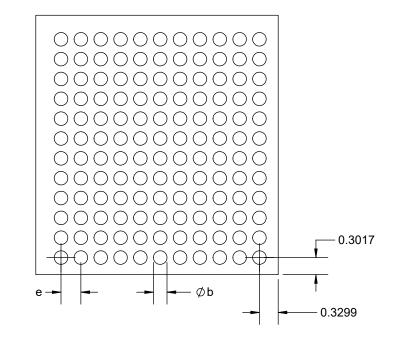
Target PCB Recommendations:

Total thickness: 1.6mm min. Plating: Gold or Solder finish PCB Pad height: Same or higher than solder mask

GT-BGA-2021 Drawing	Finish: N/A	STATUS: Released	SHEET: 2 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com		ENG: B. Schatz	DRAWN BY: M. Raske	SCALE: 8:1
		FILE: GT-BGA-2021 Dwg	DATE: 09/18/2015	

Ironwood Package Code : BGA132F





Dimensions are in millimeters.

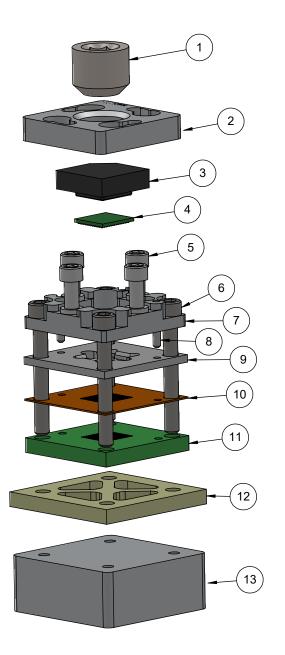
- 1. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z. 2.
- 3. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- Parallelism measurement shall exclude any effect of mark on top surface of package. 4.

DIM	MIN	MAX
Α	0.5	0.56
A1	0.17	0.2
b	0.21	0.27
D	4.25	4.30
E	4.55	4.60
е	0.	35

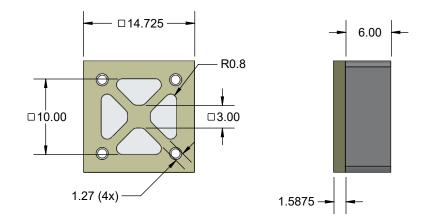
Description: Compatible Device

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

G	T-BGA-2021 Drawing	Material: N/A	STATUS: Released	SHEET: 3 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Finish: N/A Weight: 8.00	ENG: B. Schatz	DRAWN BY: M. Raske	SCALE: 15:1	
			FILE: GT-BGA-2021 Dwg	DATE: 09/18/2015	



ITEM NO.	DESCRIPTION	Material	
1	Compression Screw	Steel	
2	Socket Lid	Aluminum	
3	Compression Plate	Aluminum	
4	Compatible BGA	N/A	
5	Shoulder Screw	Steel	
6	Mounting Screw	Steel	
7	Socket Base	Aluminum	
8	Alignment Pin	Steel	
9	IC Guide	PEEK	
10	GT Elastomer	Conductive Elastomer	
11	Target PCB	N/A	
12	Insulation Plate	FR4 Standard	
13	Backing Plate	Aluminum	



INSULATION AND BACKING PLATE DETAIL

Description: Socket, Backing Plate Detail Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ± 0.03 mm [± 0.001 "], Pitches (from true position) ± 0.025 mm [± 0.001 "], substrate thickness tolerance $\pm 10\%$, all other tolerances ± 0.13 mm [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

G	T-BGA-2021 Drawing	Material: N/A	STATUS: Released	SHEET: 4 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Finish: N/A Weight: 8.00	ENG: B. Schatz	DRAWN BY: M. Raske	SCALE: 5:2	
			FILE: GT-BGA-2021 Dwg	DATE: 09/18/2015	